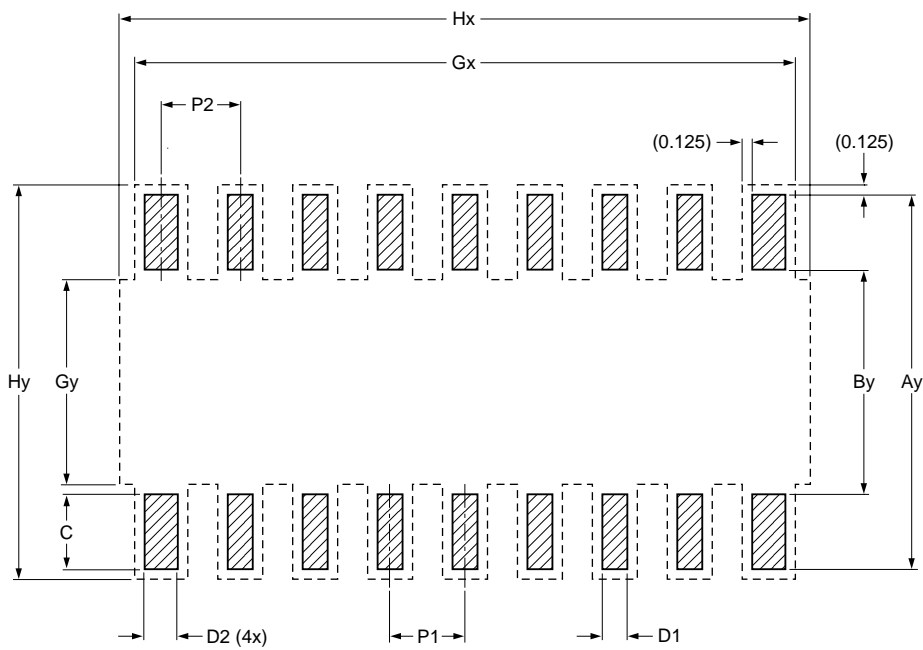




Footprint information for reflow soldering of TSSOP16 package

SOT403-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

 solder land  
 occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	5.600	5.300	5.800	7.450